

# ZVP1320FTA-VB Datasheet P-Channel 200V (D-S)MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> ( )	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
- 200	0.8 at V <sub>GS</sub> = - 10 V	- 0.80	8.0		
	0.9 at V <sub>GS</sub> =- 6.0 V	- 0.70	0.0		

#### **FEATURES**

 Halogen-free According to IEC 61249-2-21 Available

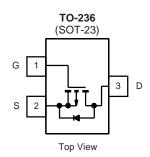


Ro

- Trench Power MOSFET
- Ultra Low On-Resistance
- Small Size

#### **APPLICATIONS**

• Active Clamp Circuits in DC/DC Power Supplies



<b>ABSOLUTE MAXIMUM RATINGS</b> T <sub>A</sub> = 25 °C, unless otherwise noted						
Parameter		Symbol	5 s	Steady State	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 200		V	
Gate-Source Voltage		$V_{GS}$	± 20			
Continuous Proin Comment /T 450 90\8 h	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	- 0.80	- 0.64		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a, b</sup>	T <sub>A</sub> = 70 °C		- 0.70	- 0.51	1	
Pulsed Drain Current		I <sub>DM</sub>	- 2.5		Α	
Continuous Source Current (Diode Conduction) <sup>a, b</sup>		I <sub>S</sub>	- 1.0	- 0.6		
Single Pulse Avalanche Current	L = 1.0 mH	I <sub>AS</sub>	4.0			
Single Pulse Avalanche Energy		E <sub>AS</sub>	1.2		mJ	
M	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.45	0.95	W	
Maximum Power Dissipation <sup>a, b</sup>	T <sub>A</sub> = 70 °C		0.8	0.48	VV	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Manipular to Archive 18	t ≤ 5 s	R <sub>thJA</sub>	75	100	°C/W	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		120	166		
Maximum Junction-to-Foot (Drain)	Steady State		40	50		

#### Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.



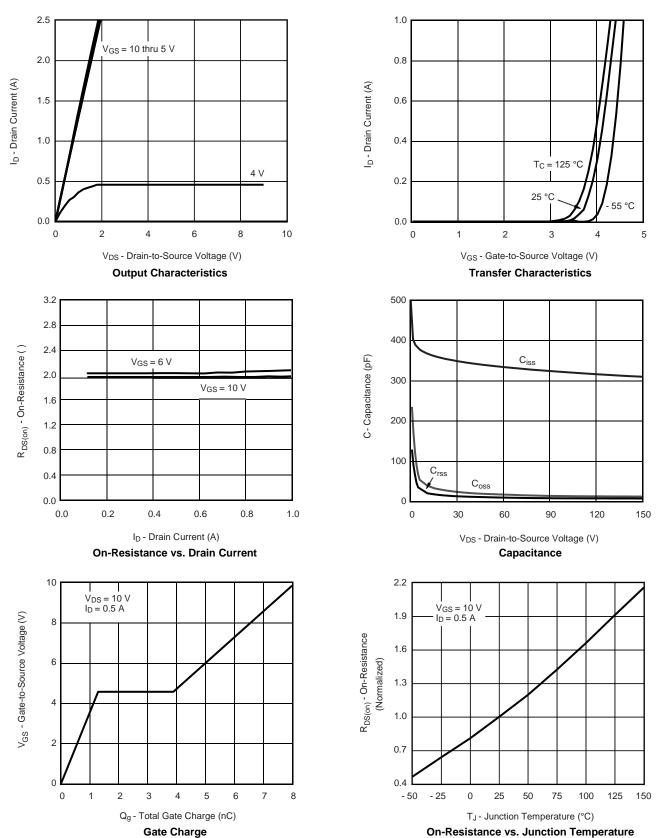
			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 200			V	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 2.5		- 4.5		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub> _	V <sub>DS</sub> = - 200 V, V <sub>GS</sub> = 0 V	- 1		- 1		
		V <sub>DS</sub> = - 200 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	μA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -15 \text{ V}, V_{GS} = 10 \text{ V}$	- 1.0			Α	
	В	$V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}$		0.80			
Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = -6.0 \text{ V}, I_D = -0.5 \text{ A}$		0.90			
Forward Transconductance <sup>a</sup>	orward Transconductance <sup>a</sup> 9 <sub>fs</sub>			1.8		S	
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> = - 1.0 A, V <sub>GS</sub> = 0 V		- 0.85	- 1.2	V	
Dynamic <sup>b</sup>							
Total Gate Charge	Qg	V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 10 V		8.0	12		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -100 \text{ V}, V_{GS} = 10 \text{ V}$ $I_{D} \cong -0.5 \text{ A}$		1.3		nC	
Gate-Drain Charge	Q <sub>gd</sub>	.b= 0.0.1		2.5			
Gate Resistance	Rg	f = 1.0 MHz		8.0		^	
Input Capacitance	C <sub>iss</sub>			370	510	pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		28			
Reverse Transfer Capacitance	C <sub>rss</sub>			16			
Switching <sup>c</sup>							
Turn-On Time	t <sub>d(on)</sub>	$t_{d(on)}$ $V_{DD} = -100 \text{ V}, R_L = 100 \land$ $I_D \cong -1.0 \text{ A}, V_{GEN} = -10 \text{ V}$		8	12	ns	
rum-on rime	t <sub>r</sub>			11	17		
Turn-Off Time	t <sub>d(off)</sub>			16	25	113	
Tuni-On Time	t <sub>f</sub>	$R_g = 6 \land$		11	17		
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	$I_F = 0.5 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$		140	200	nC	

- a. Pulse test: PW  $\leq$  300  $\mu$ s duty cycle  $\leq$  2 %. b. For DESIGN AID ONLY, not subject to production testing. c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

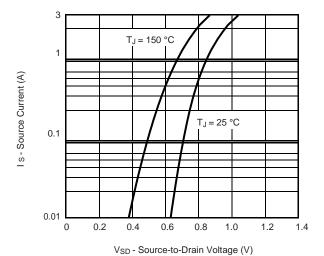


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

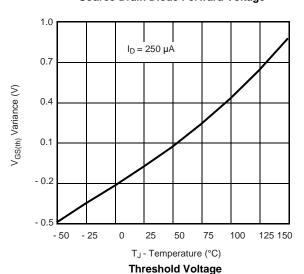




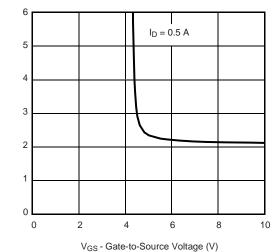
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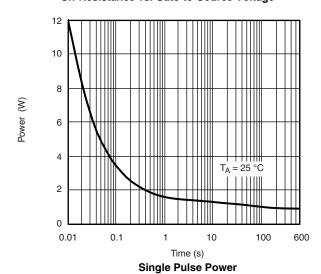
Source-Drain Diode Forward Voltage



R<sub>DS(on)</sub> - On-Resistance (<)



On-Resistance vs. Gate-to-Source Voltage

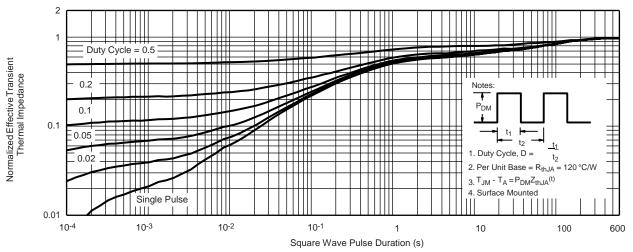


\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

Safe Operating Area



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



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